# Switching (30V, ±10A)

# **RSS100N03**

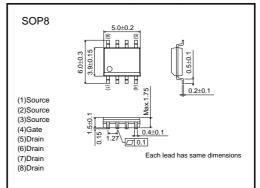
#### Features

- 1) Low on-resistance.
- 2) Built-in G-S Protection Diode.
- 3) Small and Surface Mount Package (SOP8).

#### Applications

Power switching, DC/DC converter.

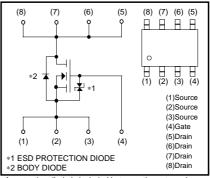
# ●External dimensions (Unit : mm)



#### **●Structure**

•Silicon N-channel MOS FET

# ●Equivalent circuit



\*A protection diode is included between the gate and the source terminals to protect the diode against static electricity when the product is in use. Use the protection circuit when the fixed voltages are exceeded.

#### ◆Absolute maximum ratings (Ta=25°C)

Parameter		Symbol	Limits	Unit	
Drain-source voltage		VDSS	30	V	
Gate-source voltage		Vgss	20	V	
Drain current	Continuous	ΙD	±10	А	
	Pulsed	IDP	±40	A *1	
Source current (Body diode)	Continuous	Is	1.6	A	
	Pulsed	Isp	6.4	A *1	
Total power dissipatino		Po	2	W *2	
Channel temperature		Tch	150	°C	
Strage temperature		Tstg	-55 to +150	°C	

<sup>\*1</sup> Pw≤10∞s, Duty cycle≤1% \*2 Mounted on a ceramic board.

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# ●Thermal resistance (Ta=25°C)

Parameter	Symbol	Limits	Unit		
Channel to ambient	Rth (ch-a)	62.5	°C / W *		

<sup>\*</sup> Mounted on a ceramic board.

# ●Electrical characteristics (Ta=25°C)

Parameter	Symbol	Min.	Тур.	Max.	Unit	Conditions
Gate-source leakage	I <sub>GSS</sub>	_	_	10	∝A	V <sub>GS</sub> =20V, V <sub>DS</sub> =0V
Drain-source breakdown voltage	V <sub>(BR)</sub> DSS	30	_	_	V	I <sub>D</sub> =1mA, V <sub>GS</sub> =0V
Zero gate voltage drain current	IDSS	-	_	10	∞A	V <sub>DS</sub> =30V, V <sub>GS</sub> =0V
Gate threshold voltage	V <sub>GS (th)</sub>	1.0	_	2.5	V	V <sub>DS</sub> =10V, I <sub>D</sub> =1mA
Static drain-source on-starte resistance		-	9.5	13.0	mΩ	I <sub>D</sub> =±10A, V <sub>GS</sub> =10V *
	RDS (on)	_	12.5	17.2		ID=±10A, VGS=4.5V *
		_	13.5	18.5		ID=±10A, VGS=4V *
Forward transfer admittance	Yfs	6.0	_	_	S	I <sub>D</sub> =±10A, V <sub>DS</sub> =10V *
Input capacitance	Ciss	_	1070	_	pF	V <sub>DS</sub> =10V
Output capacitance	Coss	-	320	_	pF	V <sub>GS</sub> =0V
Reverse transfer capacitance	Crss	_	200	_	pF	f=1MHz
Tum-on delay time	t <sub>d (on)</sub>	_	10	_	ns	I <sub>D</sub> =5A, V <sub>DD</sub> ≒15V *
Rise time	tr	_	16	_	ns	V <sub>GS</sub> =10V *
Tum-off delay time	t <sub>d (off)</sub>	_	55	_	ns	R <sub>L</sub> =3.0Ω *
Fall time	tf	_	24	_	ns	Rgs=10Ω *
Total gate charge	Qg	_	14	_	nC	Vpp≒15V *
Gate-source charge	Qgs	_	2.7	_	nC	V <sub>GS</sub> =5V *
Gate-drain charge	$Q_{gd}$	-	5.3	_	nC	I <sub>D</sub> =±10A *

<sup>\*</sup>Pulsed

#### ●Body diode characteristics (Source-Drain Characteristics) (Ta=25°C)

Parameter	Symbol	Min.	Тур.	Max.	Unit	Conditions	
Forward voltage	Vsp	-	_	1.2	V	Is=6.4A, Vgs=0V	*

<sup>\*</sup>Pulsed

### •Electrical characteristic curves

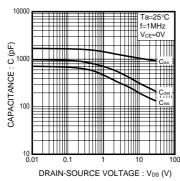


Fig.1 Typical Capacitance vs. Drain-Source Voltage

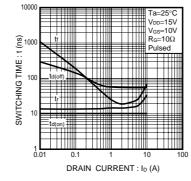


Fig.2 Switching Characteristics

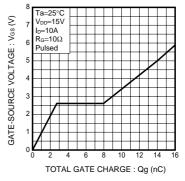


Fig.3 Dynamic Input Characteristics

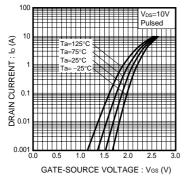


Fig.4 Typical Transfer Characteristics

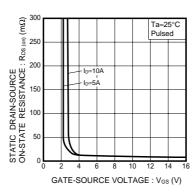


Fig.5 Static Drain-Source On-State Resistance vs. Gate-Source Voltage

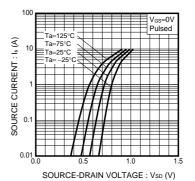


Fig.6 Source Current vs. Source-Drain Voltage

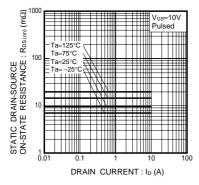


Fig.7 Static Drain-Source On-State Resistance vs. Drain Current (I)

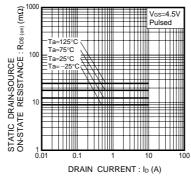


Fig.8 Static Drain-Source On-State Resistance vs. Drain Current (II)

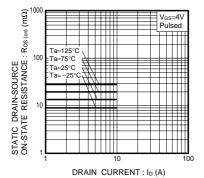


Fig.9 Static Drain-Source On-State Resistance vs. Drain Current (III)

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